



Material Content Data Sheet



Sales Product Name	TLE7244SL			Issued	25. January 2018			
MA#	MA001673952							
Package	PG-SSOP-24-7			Weight*	147.13 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.128	3.49	3.49	34856	34856
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		106	
	non noble metal	zinc	7440-66-6	0.062	0.04		423	
	non noble metal	iron	7439-89-6	1.245	0.85		8465	
wire	non noble metal	copper	7440-50-8	50.568	34.37	35.27	343700	352694
	noble metal	gold	7440-57-5	0.756	0.51	0.51	5139	5139
	encapsulation	organic material	carbon black	1333-86-4	0.171	0.12		1161
encapsulation	plastics	epoxy resin	-	7.854	5.34		53384	
	inorganic material	silicondioxide	60676-86-0	77.347	52.56	58.02	525712	580257
leadfinish	non noble metal	tin	7440-31-5	1.680	1.14	1.14	11417	11417
plating	noble metal	silver	7440-22-4	0.365	0.25	0.25	2483	2483
glue	plastics	acrylic resin	-	0.426	0.29		2894	
	noble metal	silver	7440-22-4	1.510	1.03	1.32	10260	13154
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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